MOSEL VITELIC

V53C806H HIGH PERFORMANCE 1M x 8 BIT FAST PAGE MODE CMOS DYNAMIC RAM

PRELIMINARY

HIGH PERFORMANCE	40	45	50	60
Max. RAS Access Time, (t _{RAC})	40 ns	45 ns	50 ns	60 ns
Max. Column Address Access Time, (t _{CAA})	20 ns	22 ns	24 ns	30 ns
Min. Fast Page Mode Cycle Time, (t _{PC})	23 ns	25 ns	28 ns	40 ns
Min. Read/Write Cycle Time, (t _{RC})	75 ns	80 ns	90 ns	120 ns

Features

- 1M x 8-bit organization
- Fast Page Mode for a sustained data rate of
- RAS access time: 40, 45, 50, 60 ns
- Read-Modify-Write, RAS-Only Refresh, CAS-Before-RAS Refresh capability
- Refresh Interval: 1024 cycle/16 ms
- Available in 28-pin 400 mil SOJ package
- Single +5V ±10% Power Supply
- TTL Interface

Description

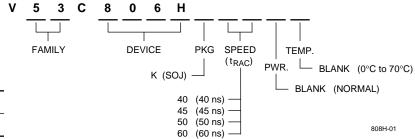
The V53C806H is a ultra high speed 1,048,576 x 8 bit CMOS dynamic random access memory. The V53C806H offers a combination of features: Fast Page Mode for high data bandwidth, and Low CMOS standby current.

All inputs and outputs are TTL compatible. Input and output capacitances are significantly lowered to allow increased system performance. Fast Page Mode operation allows random access of up to 1024 x 8 bits within a row with cycle times as fast as 23 ns. Because of static circuitry, the CAS clock is not in the critical timing path. The flow-through column address latches allow address pipelining while relaxing many critical system timing requirements.

The V53C806H is ideally suited for graphics, digital signal processing and high-performance computing systems.

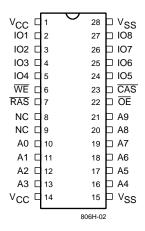
Device Usage Chart

Operating	Package Outline		Access	Γime (ns)	Power	Tomporeture		
Temperature Range	К	40	45 50		60	Std.	Temperature Mark	
0°C to 70 °C	•	•	•	•	•	•	Blank	



Description	Pkg.	Pin Count
SOJ	K	28

28-Pin SOJ PIN CONFIGURATION Top View



Pin Names

A ₀ -A ₉	Address Inputs
RAS	Row Address Strobe
CAS	Column Address Strobe
WE	Write Enable
ŌĒ	Output Enable
I/O ₁ –I/O ₈	Data Input, Output
V _{CC}	+5V Supply
V _{SS}	0V Supply
NC	No Connect

Absolute Maximum Ratings*

Ambient Temperature	
Under Bias	10°C to +80°C
Storage Temperature (plastic)	55°C to +125°C
Voltage Relative to V _{SS}	1.0 V to +7.0 V
Data Output Current	50 mA
Power Dissipation	1.4 W

*Note: Operation above Absolute Maximum Ratings can adversely affect device reliability.

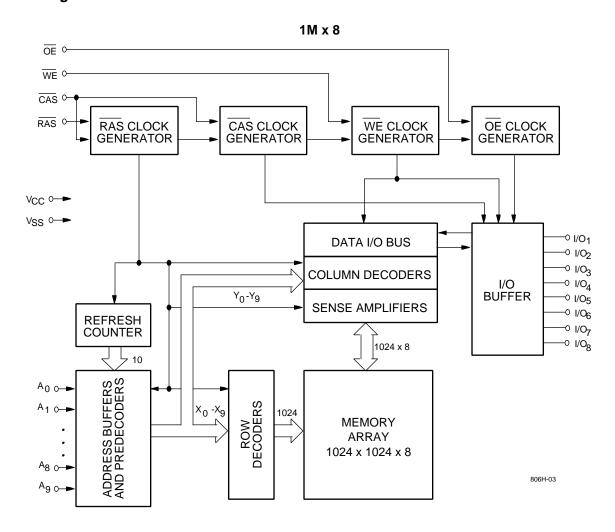
Capacitance*

 $T_A = 25$ °C, $V_{CC} = 5 \text{ V} \pm 10$ %, f = 1 MHz

Symbol	Parameter	Тур.	Max.	Unit
C _{IN1}	Address Input	3	4	pF
C _{IN2}	RAS, CAS, WE, OE	4	5	pF
C _{OUT}	Data Input/Output	5	7	pF

^{*} Note: Capacitance is sampled and not 100% tested

Block Diagram



DC and Operating Characteristics

 T_{A} = 0°C to 70°C, V_{CC} = 5 V \pm 10%, V_{SS} = 0 V, unless otherwise specified.

		Access	V53C806H						
Symbol	Parameter	Time	Min.	Min. Typ. Max.		Unit	Test Conditions	Notes	
I _{LI}	Input Leakage Current (any input pin)		-10		10	μА	$V_{SS} \le V_{IN} \le V_{CC}$		
I _{LO}	Output Leakage Current (for High-Z State)		-10		10	μА	$ \begin{aligned} & V_{SS} \leq V_{OUT} \leq V_{CC} \\ & \overline{RAS}, \overline{CAS} \text{ at } V_{IH} \end{aligned} $		
I _{CC1}	V _{CC} Supply Current,	40			220	mA	$t_{RC} = t_{RC} \text{ (min.)}$	1, 2	
	Operating	45			210				
		50			200				
		60			190				
I _{CC2}	V _{CC} Supply Current, TTL Standby				4	mA	\overline{RAS} , \overline{CAS} at V_{IH} other inputs $\geq V_{SS}$		
I _{CC3}	V _{CC} Supply Current, RAS-Only Refresh	40			220	mA	$t_{RC} = t_{RC} \text{ (min.)}$	2	
		45			210				
		50			200				
		60			190				
I _{CC4}	V _{CC} Supply Current,	40			110	mA	Minimum cycle	1, 2	
	Fast Page Mode Operation	45			100				
		50			90				
		60			80				
I _{CC5}	V _{CC} Supply Current, Standby, Output Enabled				2.0	mA	$\overline{RAS} = V_{IH}, \overline{CAS} = V_{IL}$ other inputs $\geq V_{SS}$	1	
I _{CC6}	V _{CC} Supply Current, CMOS Standby				2.0	mA	$\overline{RAS} \ge V_{CC} - 0.2 \text{ V},$ $\overline{CAS} \ge V_{CC} - 0.2 \text{ V},$ $All other inputs \ge V_{SS}$		
V _{CC}	Supply Voltage		4.5	5.0	5.5	V			
V _{IL}	Input Low Voltage		-1		0.8	V		3	
V _{IH}	Input High Voltage		2.4		V _{CC} + 1	V		3	
V _{OL}	Output Low Voltage				0.4	V	I _{OL} = 4.2 mA		
V _{OH}	Output High Voltage		2.4			V	I _{OH} = -5 mA		

AC Characteristics

 T_A = 0°C to 70°C, V_{CC} = 5 V ±10%, V_{SS} = 0V unless otherwise noted AC Test conditions, input pulse levels 0 to 3V

			4	0	4	5	5	0	6	60		
#	Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit	Notes
1	t _{RAS}	RAS Pulse Width	40	75K	45	75K	50	75K	60	75K	ns	
2	t _{RC}	Read or Write Cycle Time	75		80		90		110		ns	
3	t _{RP}	RAS Precharge Time	25		25		30		40		ns	
4	t _{CSH}	CAS Hold Time	40		45		50		60		ns	
5	t _{CAS}	CAS Pulse Width	12		13		14		15		ns	
6	t _{RCD}	RAS to CAS Delay	17	28	18	32	19	36	20	43	ns	
7	t _{RCS}	Read Command Setup Time	0		0		0		0		ns	4
8	t _{ASR}	Row Address Setup Time	0		0		0		0		ns	
9	t _{RAH}	Row Address Hold Time	7		8		9		10		ns	
10	t _{ASC}	Column Address Setup Time	0		0		0		0		ns	
11	t _{CAH}	Column Address Hold Time	5		6		7		10		ns	
12	t _{RSH (R)}	RAS Hold Time (Read Cycle)	12		13		14		15		ns	
13	t _{CRP}	CAS to RAS Precharge Time	5		5		5		5		ns	
14	t _{RCH}	Read Command Hold Time Referenced to CAS	0		0		0		0		ns	5
15	t _{RRH}	Read Command Hold Time Referenced to RAS	0		0		0		0		ns	5
16	t _{ROH}	RAS Hold Time Referenced to OE	8		9		10		10		ns	
17	t _{OAC}	Access Time from OE		12		13		14		17	ns	
18	t _{CAC}	Access Time from CAS		12		13		14		17	ns	6, 7
19	t _{RAC}	Access Time from RAS		40		45		50		60	ns	6, 8, 9
20	t _{CAA}	Access Time from Column Address		20		22		24		30	ns	6, 7, 10
21	t _{LZ}	CAS to Low-Z Output	0		0		0		0		ns	16
22	t _{HZ}	Output buffer turn-off delay time	0	6	0	7	0	8	0	10	ns	16
23	t _{AR}	Column Address Hold Time from RAS	30		35		40		45		ns	
24	t _{RAD}	RAS to Column Address	12	20	13	23	14	26	15	30	ns	11
		Delay Time										
25	t _{RSH (W)}	RAS or CAS Hold Time in Write Cycle	12		13		14		15		ns	
26	t _{CWL}	Write Command to CAS Lead Time	12		13		14		15		ns	
27	t _{WCS}	Write Command Setup Time	0		0		0		0		ns	12, 13
28	t _{WCH}	Write Command Hold Time	5		6		7		10		ns	
29	t _{WP}	Write Pulse Width	5		6		7		10		ns	

AC Characteristics (Cont'd)

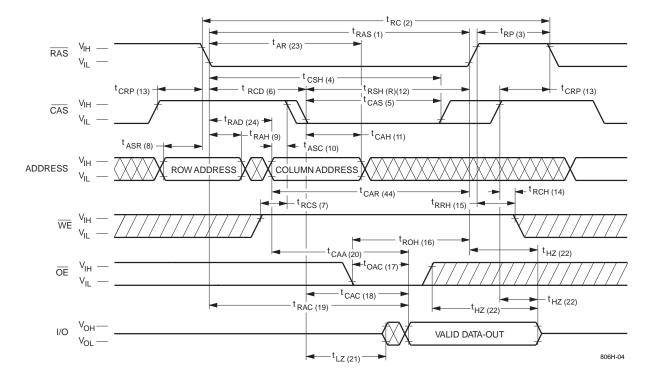
			4	0	4	5	50		60			
#	Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit	Notes
30	t _{WCR}	Write Command Hold Time from RAS	30		35		40		45		ns	
31	t _{RWL}	Write Command to RAS Lead Time	12		13		14		15		ns	
32	t _{DS}	Data in Setup Time	0		0		0		0		ns	14
33	t _{DH}	Data in Hold Time	5		6		7		10		ns	14
34	t _{WOH}	Write to OE Hold Time	6		7		8		10		ns	14
35	t _{OED}	OE to Data Delay Time	6		7		8		10		ns	14
36	t _{RWC}	Read-Modify-Write Cycle Time	110		115		130		170		ns	
37	t _{RRW}	Read-Modify-Write Cycle RAS Pulse Width	75		80		87		105		ns	
38	t _{CWD}	CAS to WE Delay	30		32		34		40		ns	12
39	t _{RWD}	RAS to WE Delay in Read-Modify- Write Cycle	58		62		68		85		ns	12
40	t _{CRW}	CAS Pulse Width (RMW)	48		50		52		65		ns	
41	t _{AWD}	Col. Address to WE Delay	38		41		42		58		ns	12
42	t _{PC}	Fast Page Mode Read or Write Cycle Time	23		25		28		40		ns	
43	t _{CP}	CAS Precharge Time	5		6		7		8		ns	
44	t _{CAR}	Column Address to RAS Setup Time	20		22		24		30		ns	
45	t _{CAP}	Access Time from Column Precharge		23		25		27		34	ns	7
46	t _{DHR}	Data in Hold Time Referenced to RAS	30		35		40		50		ns	
47	t _{CSR}	CAS Setup Time CAS-before-RAS Refresh	10		10		10		10		ns	
48	t _{RPC}	RAS to CAS Precharge Time	0		0		0		0		ns	
49	t _{CHR}	CAS Hold Time CAS-before-RAS Refresh	8		10		12		15		ns	
50	t _{PCM}	Fast Page Mode Read-Modify-Write Cycle Time	60		65		70		85		ns	
51	t _T	Transition Time (Rise and Fall)	3	50	3	50	3	50	3	50	ns	15
52	t _{REF}	Refresh Interval (1024 Cycles)		16		16		16		16	ms	

Notes:

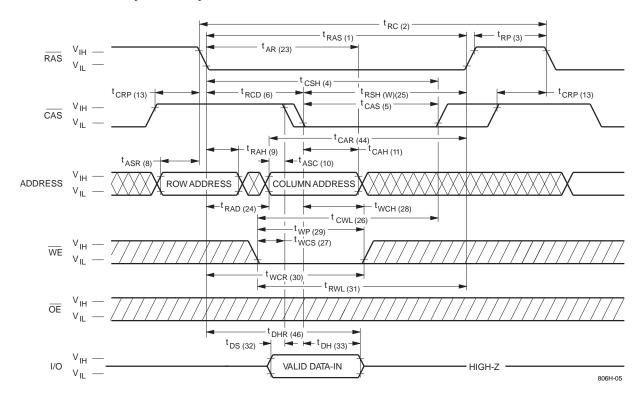
 I_{CC} is dependent on output loading when the device output is selected. Specified I_{CC} (max.) is measured with the output open.

- 2. I_{CC} is dependent upon the number of address transitions. Specified I_{CC} (max.) is measured with a maximum of two transitions per address cycle in Fast Page Mode.
- Specified V_{IL} (min.) is steady state operating. During transitions, V_{IL} (min.) may undershoot to −1.0 V for a period not to exceed 20 ns. All AC parameters are measured with V_{IL} (min.) ≥ V_{SS} and V_{IH} (max.) ≤ V_{CC}.
- t_{RCD} (max.) is specified for reference only. Operation within t_{RCD} (max.) limits insures that t_{RAC} (max.) and t_{CAA} (max.) can be met. If t_{RCD} is greater than the specified t_{RCD} (max.), the access time is controlled by t_{CAA} and t_{CAC}.
- 5. Either t_{RRH} or t_{RCH} must be satisified for a Read Cycle to occur.
- 6. Measured with a load equivalent to two TTL inputs and 50 pF.
- 7. Access time is determined by the longest of t_{CAA} , t_{CAC} and t_{CAP} .
- Assumes that t_{RAD} ≤ t_{RAD} (max.). If t_{RAD} is greater than t_{RAD} (max.), t_{RAC} will increase by the amount that t_{RAD} exceeds t_{RAD} (max.).
- Assumes that t_{RCD} ≤ t_{RCD} (max.). If t_{RCD} is greater than t_{RCD} (max.), t_{RAC} will increase by the amount that t_{RCD} exceeds t_{RCD} (max.).
- 10. Assumes that $t_{RAD} \ge t_{RAD}$ (max.).
- 11. Operation within the t_{RAD} (max.) limit ensures that t_{RAC} (max.) can be met. t_{RAD} (max.) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD} (max.) limit, the access time is controlled by t_{CAA} and t_{CAC}.
- 12. t_{WCS}, t_{RWD}, t_{AWD} and t_{CWD} are not restrictive operating parameters.
- 13. t_{WCS} (min.) must be satisfied in an Early Write Cycle.
- 14. t_{DS} and t_{DH} are referenced to the latter occurrence of \overline{CAS} or \overline{WE} .
- 15. t_T is measured between V_{IH} (min.) and V_{IL} (max.). AC-measurements assume t_T = 3 ns .
- Assumes a three-state test load (5 pF and a 380 Ohm Thevenin equivalent).
- 17. An initial 200 μs pause and 8 RAS-containing cycles are required when exiting an extended period of bias without clocks. An extended period of time without clocks is defined as one that exceeds the specified Refresh Interval.

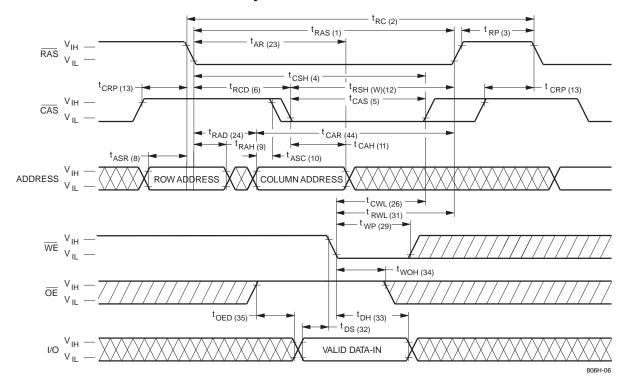
Waveforms of Read Cycle



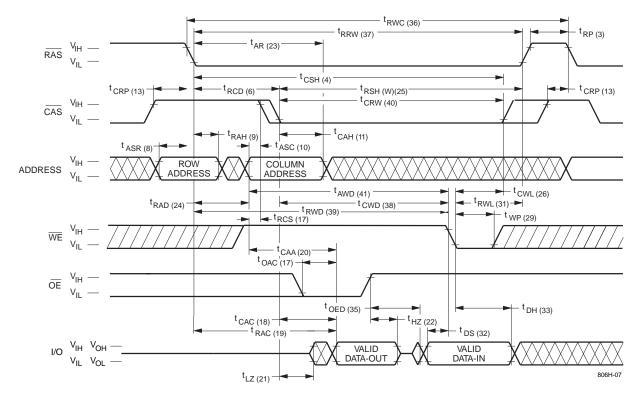
Waveforms of Early Write Cycle



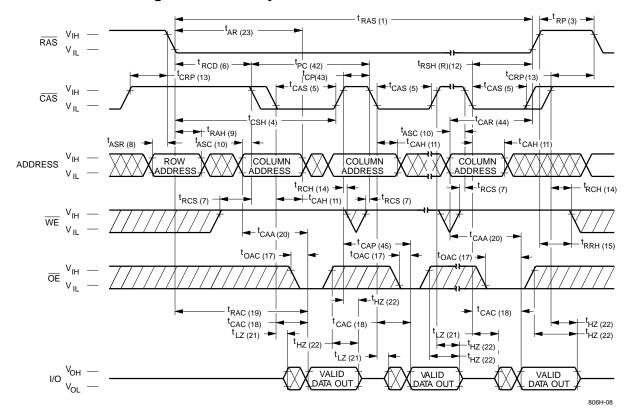
Waveforms of OE-Controlled Write Cycle



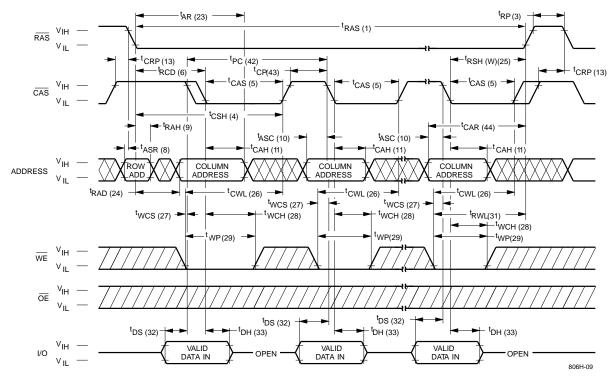
Waveforms of Read-Modify-Write Cycle



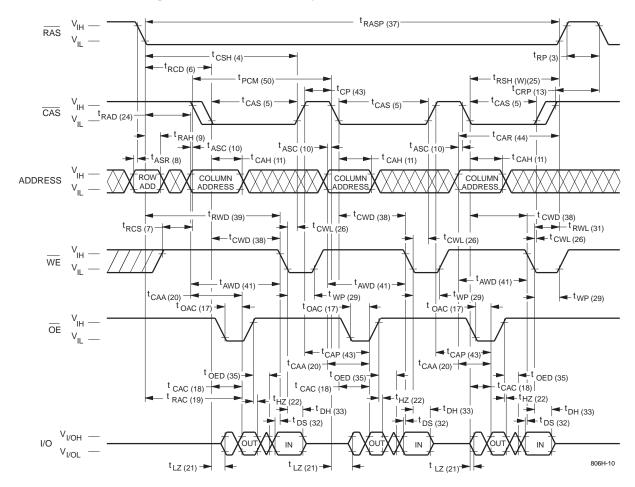
Waveforms of Fast Page Mode Read Cycle



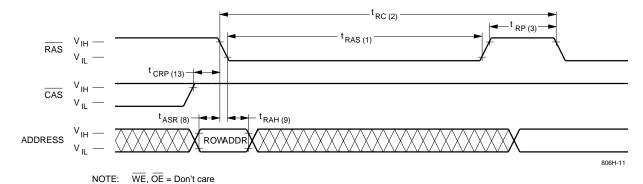
Waveforms of Fast Page Mode Write Cycle



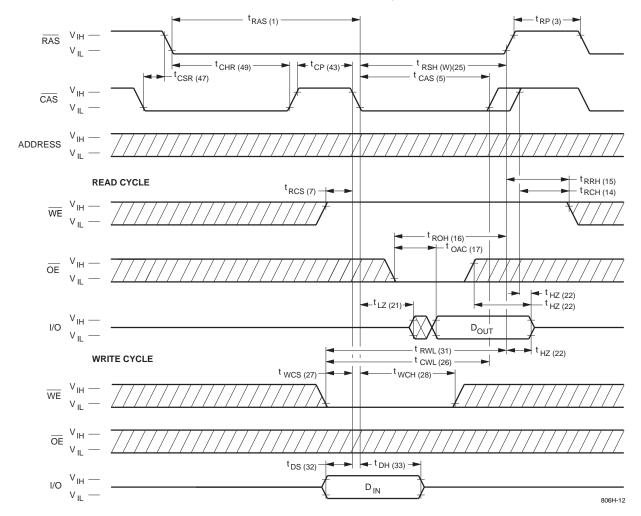
Waveforms of Fast Page Mode Read-Write Cycle



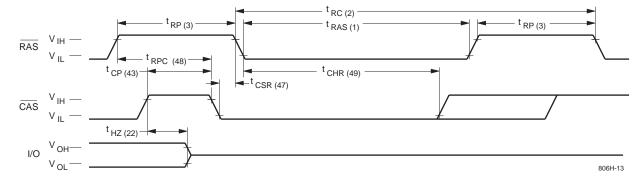
Waveforms of RAS-Only Refresh Cycle



Waveforms of CAS-before-RAS Refresh Counter Test Cycle

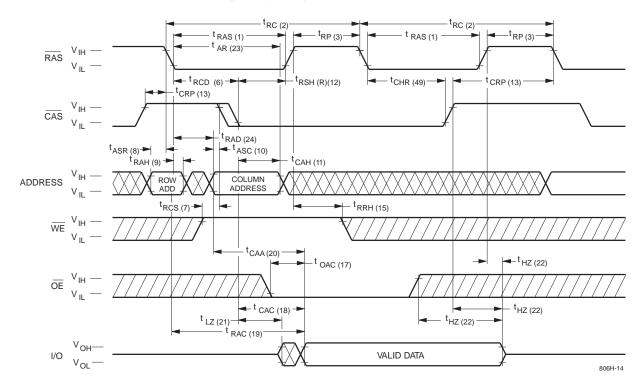


Waveforms of CAS-before-RAS Refresh Cycle

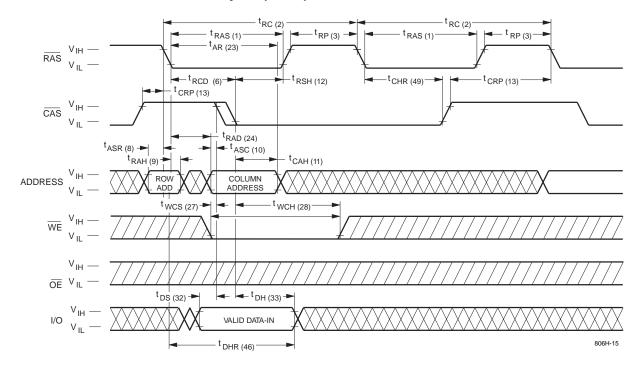


NOTE: \overline{WE} , \overline{OE} , $A_0 - A_9 = Don't$ care

Waveforms of Hidden Refresh Cycle (Read)



Waveforms of Hidden Refresh Cycle (Write)



Functional Description

The V53C806H is a CMOS dynamic RAM optimized for high data bandwidth, low power applications. It is functionally similar to a traditional dynamic RAM. The V53C806H reads and writes data by multiplexing an 20-bit address into a 10-bit row and a 10-bit column address. The row address is latched by the Row Address Strobe (RAS). The column address "flows through" an internal address buffer and is latched by the Column Address Strobe (CAS). Because access time is primarily dependent on a valid column address rather than the precise time that the CAS edge occurs, the delay time from RAS to CAS has little effect on the access time.

Memory Cycle

A memory cycle is initiated by bringing \overline{RAS} low. Any memory cycle, once initiated, must not be ended or aborted before the minimum t_{RAS} time has expired. This ensures proper device operation and data integrity. A new cycle must not be initiated until the minimum precharge time t_{RP}/t_{CP} has elapsed.

Read Cycle

A Read cycle is performed by holding the Write Enable (WE) signal High during a $\overline{RAS}/\overline{CAS}$ operation. The column address must be held for a minimum specified by t_{AR} . Data Out becomes valid only when t_{OAC} , t_{RAC} , t_{CAA} and t_{CAC} are all satisifed. As a result, the access time is dependent on the timing relationships between these parameters. For example, the access time is limited by t_{CAA} when t_{RAC} , t_{CAC} and t_{OAC} are all satisfied.

Write Cycle

A Write Cycle is performed by taking $\overline{\text{WE}}$ and $\overline{\text{CAS}}$ low during a $\overline{\text{RAS}}$ operation. The column address is latched by $\overline{\text{CAS}}$. The Write Cycle can be $\overline{\text{WE}}$ controlled or $\overline{\text{CAS}}$ controlled depending on whether $\overline{\text{WE}}$ or $\overline{\text{CAS}}$ falls later. Consequently, the input data must be valid at or before the falling edge of $\overline{\text{WE}}$ or $\overline{\text{CAS}}$, whichever occurs last. In the $\overline{\text{CAS}}$ -controlled Write Cycle, when the leading edge of $\overline{\text{WE}}$ occurs prior to the $\overline{\text{CAS}}$ low transition, the I/O data pins will be in the High-Z state at the beginning of the Write function. Ending the Write with $\overline{\text{RAS}}$ or $\overline{\text{CAS}}$ will maintain the output in the High-Z state.

In the $\overline{\text{WE}}$ controlled Write Cycle, $\overline{\text{OE}}$ must be in the high state and t_{OED} must be satisfied.

Fast Page Mode Operation

Fast Page Mode operation permits all 1024 columns within a selected row of the device to be randomly accessed at a high data rate. Maintaining RAS low while performing successive CAS cycles retains the row address internally and eliminates the need to reapply it for each cycle. The column address buffer acts as a transparent or flow-through latch while CAS is high. Thus, access begins from the occurrence of a valid column address rather than from the falling edge of \overline{CAS} , eliminating t_{ASC} and t_T from the critical timing path. CAS latches the address into the column address buffer and acts as an output enable. During Fast Page Mode operation, Read, Write, Read-Modify-Write or Read-Write-Read cycles are possible at random addresses within a row. Following the initial entry cycle into Fast Page Mode, access is t_{CAA} or t_{CAP} controlled. If the column address is valid prior to the rising edge of \overline{CAS} , the access time is referenced to the \overline{CAS} rising edge and is specified by t_{CAP}. If the column address is valid after the rising CAS edge, access is timed from the occurrence of a valid address and is specified by t_{CAA}. In both cases, the falling edge of CAS latches the address and enables the output.

Fast Page Mode provides a sustained data rate of 43 MHz for applications that require high data rates such as bit-mapped graphics or high-speed signal processing. The following equation can be used to calculate the maximum data rate:

$$\text{Data Rate } = \frac{1024}{t_{RC} + 1023 \times t_{PC}}$$

Data Output Operation

The V53C806H Input/Output is controlled by \overline{OE} , \overline{CAS} , \overline{WE} and \overline{RAS} . A \overline{RAS} low transition enables the transfer of data to and from the selected row address in the Memory Array. A \overline{RAS} high transition disables data transfer and latches the output data if the output is enabled. After a memory cycle is initiated with a \overline{RAS} low transition, a \overline{CAS} low transition enables the internal I/O path. A \overline{CAS} high transition or \overline{RAS} high transition, whichever occurs later, disables the I/O path and the output driver if it is enabled. A \overline{CAS} low transition while \overline{RAS} is high has no effect on the I/O data path or on the output drivers. The output drivers, when otherwise enabled, can be disabled by holding \overline{OE} high. The \overline{OE} signal

has no effect on any data stored in the output latches. A $\overline{\text{WE}}$ low level can also disable the output drivers. During a Write cycle, if $\overline{\text{WE}}$ goes low at a time when the $\overline{\text{CAS}}$ is low, it is necessary to use $\overline{\text{OE}}$ to disable the output drivers prior to the $\overline{\text{WE}}$ low transition to allow Data In Setup Time (t_{DS}) to be satisfied.

To retain data, 1024 Refresh Cycles are required in each 16 ms period. There are two ways to refresh the memory:

- By clocking each of the 1024 row addresses (A₀ through A₉) with RAS at least once every 16 ms. Any Read, Write, Read-Modify-Write or RAS-only cycle refreshes the addressed row.
- Using a CAS-before-RAS Refresh Cycle. If CAS makes a transition from low to high to low after the previous cycle and before RAS falls, CAS-before-RAS refresh is activated. The V53C806H uses the output of an internal 10-bit counter as the source of row addresses and ignore external address inputs.

CAS-before-RAS is a "refresh-only" mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle. A CAS-before-RAS counter test mode is provided to ensure reliable operation of the internal refresh counter.

Data Retention Mode

The V53C806H offers a CMOS standby mode that is entered by causing the \overline{RAS} clock to swing between a valid V_{IL} and an "extra high" V_{IH} within 0.2 V of $V_{CC}.$ While the \overline{RAS} clock is at the extra high level, the V53C806H power consumption is reduced to the low I_{CC6} level. Overall I_{CC} consumption when operating in this mode can be calculated as follows:

$$I = \frac{(t_{RC}) \times (I_{CC1}) + (t_{RX} - t_{RC}) \times (I_{CC6})}{t_{RX}}$$

Where: t_{RC} = Refresh Cycle Time t_{RX} = Refresh Interval/1024

Power-On

After application of the V_{CC} supply, an initial pause of 200 μs is required followed by a minimum of 8 initialization cycles (any combination of cycles containing a \overline{RAS} clock). Eight initialization cycles are required after extended periods of bias without clocks (greater than the Refresh Interval).

During Power-On, the V_{CC} current requirement of the V53C806H is dependent on the input levels of \overline{RAS} and \overline{CAS} . If \overline{RAS} is low during Power-On, the device will go into an active cycle and I_{CC} will exhibit current transients. It is recommended that \overline{RAS} and \overline{CAS} track with V_{CC} or be held at a valid V_{IH} during Power-On to avoid current surges.

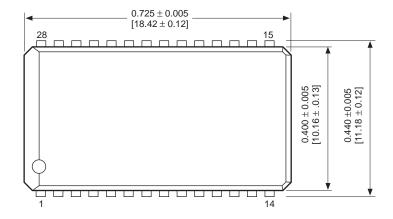
Table 1. V53C806H Data Output
Operation for Various Cycle Types

Cycle Type	I/O State
Read Cycles	Data from Addressed Memory Cell
CAS-Controlled Write Cycle (Early Write)	High-Z
WE-Controlled Write Cycle (Late Write)	OE Controlled. High OE = High-Z I/Os
Read-Modify-Write Cycles	Data from Addressed Memory Cell
Fast Page Mode Read	Data from Addressed Memory Cell
Fast Page Mode Write Cycle (Early Write)	High-Z
Fast Read-Modify-Write Cycle	Data from Addressed Memory Cell
RAS-only Refresh	High-Z
CAS-before-RAS Refresh Cycle	Data remains as in previous cycles
CAS-only Cycles	High-Z

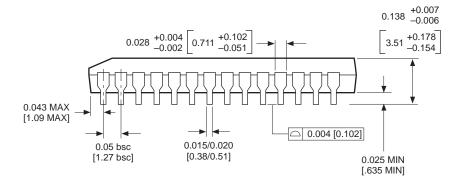
Package Diagrams

28-Pin Plastic SOJ

Unit in inches [mm]







MOSEL VITELIC

WORLDWIDE OFFICES

V53C806H

U.S.A.

3910 NORTH FIRST STREET SAN JOSE, CA 95134 PHONE: 408-433-6000 FAX: 408-433-0952

HONG KONG

19 DAI FU STREET TAIPO INDUSTRIAL ESTATE TAIPO, NT, HONG KONG PHONE: 852-2665-4883 FAX: 852-2664-7535

TAIWAN

7F, NO. 102 MIN-CHUAN E. ROAD, SEC. 3 TAIPEI

PHONE: 886-2-2545-1213 FAX: 886-2-2545-1209

1 CREATION ROAD I SCIENCE BASED IND. PARK HSIN CHU, TAIWAN, R.O.C. PHONE: 886-3-578-3344 FAX: 886-3-579-2838

SINGAPORE

10 ANSON ROAD #23-13 INTERNATIONAL PLAZA SINGAPORE 079903 PHONE: 65-3231801 FAX: 65-3237013

JAPAN

WBG MARINE WEST 25F 6, NAKASE 2-CHOME MIHAMA-KU, CHIBA-SHI CHIBA 261-71

PHONE: 81-43-299-6000 FAX: 81-43-299-6555

IRELAND & UK

BLOCK A UNIT 2 BROOMFIELD BUSINESS PARK MALAHIDE CO. DUBLIN, IRELAND PHONE: +353 1 8038020 FAX: +353 1 8038049

GERMANY (CONTINENTAL EUROPE & ISRAEL)

71083 HERRENBERG BENZSTR. 32 GERMANY

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U.S. SALES OFFICES

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